



Samsung and Micron have teamed up to form the Hybrid Memory Cube Consortium (HMCC) which aims to develop and promote the use of an open interface for products which make use of Hybrid Memory Cube technology. Hybrid Memory Cube technology stacks DRAM dies which increases performance by 15x and decreases energy usage by up to 70%.

“HMC brings a new level of capability to memory that provides exponential performance and efficiency gains that will redefine the future of memory. Guidance by the industry consortium will help drive the fastest possible adoption of the technology, resulting in what we believe will be radical improvements to computing systems.” said Robert Feurle, VP for DRAM Marketing at Micron.

Source: Tech Connect (<http://www.tcmagazine.com/tcm/news/misc/41092/samsung-and-micron-team-push-hybrid-memory-cube-technology>)

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